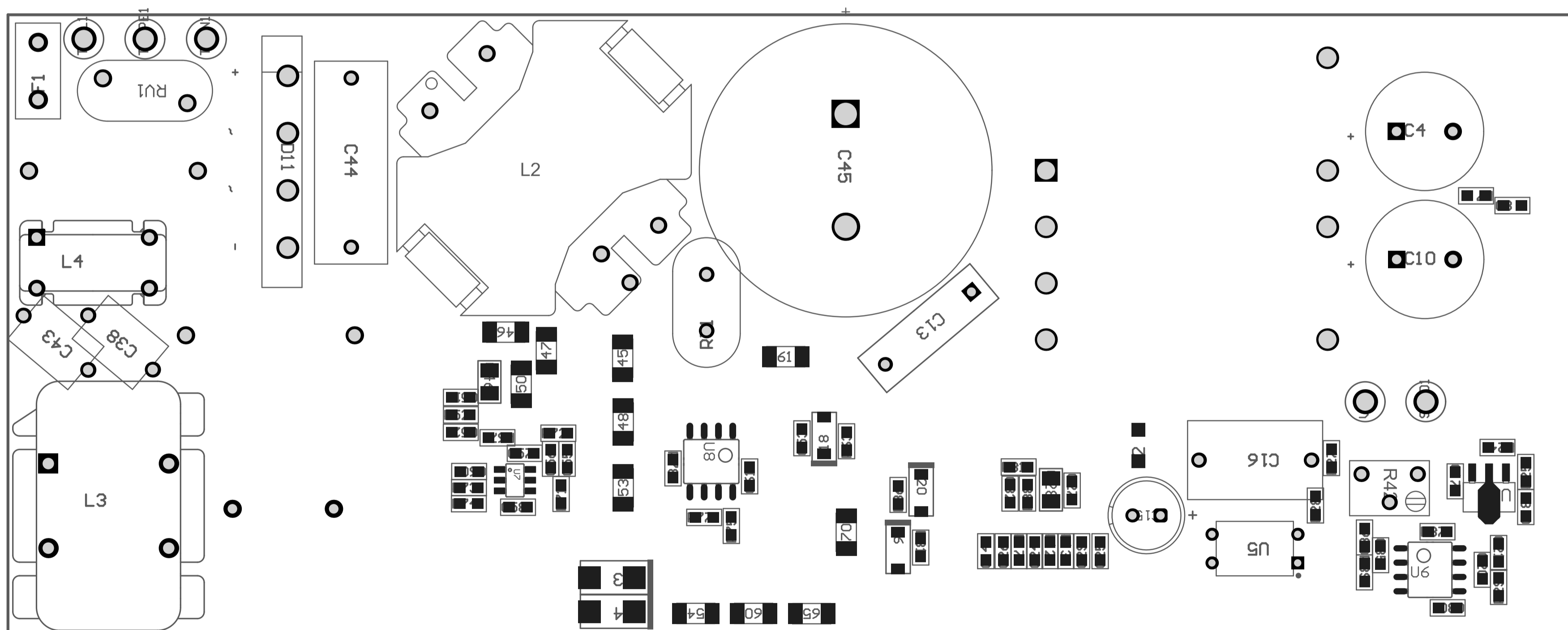


1. HS4 & HS5 Placement Instructions:

- a. Cut the Heat Sink into two equal vertical halves.
 - b. Trim the Mounting lead to fit in the PCB Mounting Hole.
2. For all jumpers (JP1 to JP8) use thin insulated wire to mount across the nodes.



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.

ASSEMBLY VARIANT: 001

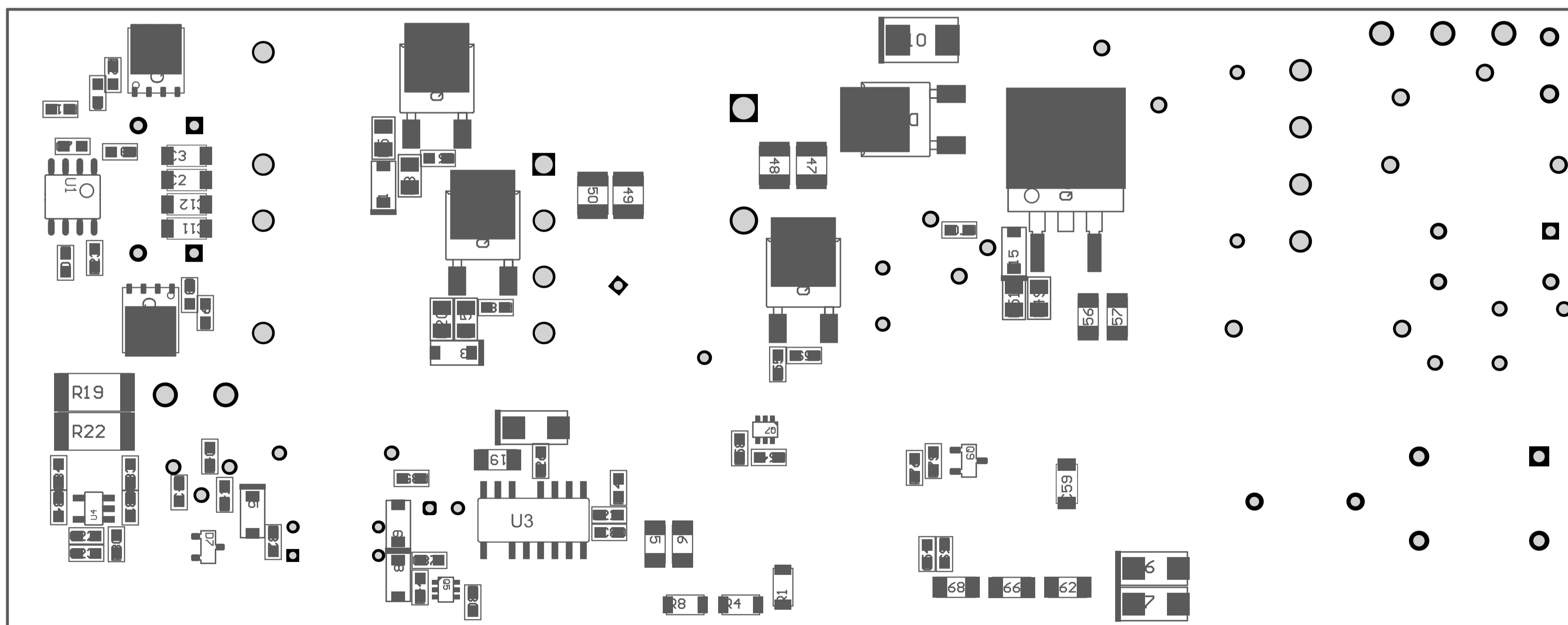
Z24 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

Z23 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

Z22 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.

Z21 ■ Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-010038	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M5 Assembly Top	TID #: TIDA-010038		
PLOT NAME = Top LayerAssembly Drawing	GENERATED :	2018/11/29 9:51:46	TEXAS INSTRUMENTS



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.

ASSEMBLY VARIANT:

001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: TIDA-010038	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M6 Assembly Bottom	TID #: TIDA-010038		
PLOT NAME = Bottom LayerAssembly Drawing	GENERATED :	2018/11/29 9:51:46	TEXAS INSTRUMENTS

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